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(71) Applicant: ROHM CO LTD

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(72) Inventor: ISHINAGA HIROMOTO

(54) BACK MOUNT CHIP TYPE LIGHT EMITTING DEVICE

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(57) Abstract:

PROBLEM TO BE SOLVED: To enable outputting a light having uniform intensity in a side surface direction of a resin mold.

SOLUTION: This back mount chip type light emitting device 10 contains a chip substrate 12 on which connecting electrodes 14a and 14b are formed, and an LED chip 16 is bonded to the connecting electrodes 14a and 14b. Resin mold 20 which is formed so as to cover the LED chip 16 is arranged on an upper surface 12a of the chip substrate 12. A recessed part 26 is formed in the central part of an upper surface of the resin mold 20. A light outputted from the LED chip 16 is totally reflected by a reflecting surface of the resin mold 20 and outputted in the side surface direction of the resin mold 20.

